Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A method for preventing wafer breakage in a wet processing tank comprising:

providing a wet processing tank <u>within a protection bath</u>, wherein said wafer is to be placed within said wet processing tank;

providing a sensor within said wet processing tank, wherein said sensor continuously counts bubbles formed within said wet processing tank in a time interval; and

querying said sensor, wherein if a bubble count within said time interval exceeds a trigger point, an alarm is given and said wafer is not placed into said wet processing tank.

2. (original) The method according to claim 1 further comprising turning on said sensor when chemical circulation occurs within said wet processing tank.

3. (previously presented) The method according to claim 1 further comprising checking if said sensor emits an "OFF" signal, wherein if said "OFF" signal is emitted for more than a threshold time period, said alarm is given and said wafer is not placed into said wet processing tank.

4. (original) The method according to claim 1 wherein said wet processing comprises wet stripping, wet etching, or rinsing.

5. (original) The method according to claim 1 wherein said bubbles are caused by boiling of liquid within said wet processing tank.

6. (original) The method according to claim 1 wherein said bubbles are caused by air being sucked into a circulation loop and thus into said wet processing tank.

7. (previously presented) The method according to claim 2 further comprising providing an outer tank surrounding said wet processing tank, wherein said chemical circulation comprises a chemical liquid circulating out of said outer tank, through a pump, and into said wet processing tank.

8. (original) The method according to claim 7 wherein said chemical liquid further travels through a heater, a filter, and several air valves.

9. (original) The method according to claim 7 wherein said chemical liquid travels through said sensor prior to traveling through said pump.

10. (withdrawn) A wet processing system comprising:

a wet processing tank wherein a wafer is to be placed within said wet processing tank;

a sensor within said wet processing tank wherein said sensor continuously counts bubbles formed within said wet processing tank in a time interval; and

an alarm wherein if a bubble count within said time interval exceeds a trigger point, then said alarm is triggered and said wafer is not placed into said wet processing tank.

11. (withdrawn) The system according to claim 10 wherein said sensor is turned on when chemical circulation occurs within said wet processing tank.

12. (withdrawn) The system according to claim 10 wherein if said sensor emits an "OFF" signal for more than a threshold time period, then said alarm is given and said wafer is not placed into said wet processing tank.

13. (withdrawn) The system according to claim 10 wherein said wet processing comprises wet stripping, wet etching, or rinsing.

14. (withdrawn) The system according to claim 10 wherein said bubbles are caused by boiling of liquid within said wet processing tank.

15. (withdrawn) The system according to claim 10 wherein said bubbles are caused by air being sucked into a circulation loop and thus into said wet processing tank.

16. (withdrawn) The system according to claim 10 further comprising:

an outer tank surrounding said wet processing tank;

a de-ionized water inlet into said outer tank; and

a circulation loop comprising a chemical liquid circulating out of said outer tank, through a pump, and into said wet processing tank wherein said chemical liquid travels through said sensor prior to traveling through said pump.

17. (withdrawn) The system according to claim 16 wherein said circulation loop further comprises:

a plurality of air valves;

a heater;

a filter; and

a drain.

18. (withdrawn) The system according to claim 16 wherein said wet processing tank overflows into said outer tank.

19. (currently amended) A method for preventing wafer breakage in a wet processing tank comprising:

providing a wet processing tank within a protection bath, comprising a protection tank within which is provided an inner tank and an outer tank surrounding said inner tank, wherein a plurality of wafers are to be placed within said inner tank;

providing a chemical circulation loop comprising a chemical liquid circulating out of said outer tank, through a pump, and into said inner tank;

providing a sensor within said chemical circulation loop, wherein said chemical liquid travels through said sensor prior to traveling through said pump, wherein said sensor continuously counts bubbles formed within said inner tank in a time interval; and

querying said sensor, wherein if a bubble count within said time interval exceeds a trigger point, an alarm is given and said plurality of wafers are not placed into said inner tank.

20. (original) The method according to claim 19 further comprising turning on said sensor when chemical circulation occurs within said chemical circulation loop.

21. (previously presented) The method according to claim 19 further comprising checking if said sensor emits an "OFF" signal, wherein if said "OFF" signal is emitted for more than a threshold time period, said alarm is given and said plurality of wafers are not placed into said inner tank.

22. (original) The method according to claim 19 wherein said wet processing comprises wet stripping, wet etching, or rinsing.

23. (previously presented) The method according to claim 19 wherein said bubbles are caused by boiling of liquid within said inner or outer tanks.

24. (original) The method according to claim 19 wherein said bubbles are caused by air being sucked into said circulation loop.

25. (original) The method according to claim 19 wherein said chemical liquid further travels through a heater, a filter, and several air valves.